

AMENDMENT TRANSMITTAL LETTER (Large Entity)Applicant(s): **Hyun-don OH et al.**

Docket No.

SEC.836

Serial No.

09/939,556

Filing Date

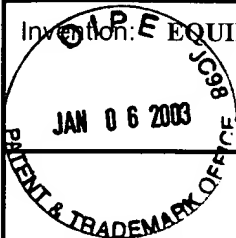
28 August 2001

Examiner

Scott B. GEYER

Group Art Unit

2829

Invention: **EQUIPMENT FOR FABRICATING A SEMICONDUCTOR PRODUCT****TO THE ASSISTANT COMMISSIONER FOR PATENTS:**

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

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TECHNOLOGY CENTER 2800**CLAIMS AS AMENDED**

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	11 -	12 =	0 x	\$18.00	\$0.00
INDEP. CLAIMS	3 -	3 =	0 x	\$84.00	\$0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00

- ☒ No additional fee is required for amendment.
- ☐ Please charge Deposit Account No. _____ in the amount of _____
A duplicate copy of this sheet is enclosed.
- ☐ A check in the amount of _____ to cover the filing fee is enclosed.
- ☒ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. **50-0238**
A duplicate copy of this sheet is enclosed.
- ☒ Any additional filing fees required under 37 C.F.R. 1.16.
- ☐ Any patent application processing fees under 37 CFR 1.17.

SignatureDated: **6 January 2003****KENNETH D. SPRINGER**

REG. NO.: 39,843

VOLENTINE FRANCO, PLLC
12200 SUNRISE VALLEY DRIVE, SUITE 150
RESTON, VA 20191

TEL. NO.: (703) 715-0870

I certify that this document and fee is being deposited on _____ with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

Signature of Person Mailing Correspondence

Typed or Printed Name of Person Mailing Correspondence

CC:

AMENDMENT TRANSMITTAL LETTER (Large Entity)

Applicant(s): Hyun-don OH et al.

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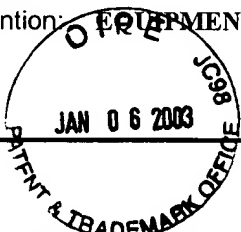
Examiner

Scott B. GEYER

JAN - 7 2003 Art Unit

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TECHNOLOGY CENTER 2800

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT APPLICATION of:

Hyun-don OH et al.

Group Art Unit: 2829

Serial No.: 09/939,556

Examiner: Scott B. GEYER

Filed: 28 August 2001

EQUIPMENT FOR FABRICATING
A SEMICONDUCTOR PRODUCT

4/A
C. Stolz
1-9-03

AMENDMENT

Honorable Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated 4 October 2002, the period for response to which is 4 January 2003, please amend the above-identified patent application as follows:

IN THE CLAIMS:

Please substitute the following claims for the pending claims with the same claim numbers.

1. (Amended) A semiconductor fabricating device, comprising:

an adhesion unit installed in a production line, the adhesion unit having an adhesion chamber that supplies an adhesion enhancing material that reinforces